



Material Content Data Sheet



Sales Product Name	TLE4287G			Issued		28. August 2013		
MA#	MA000970034							
Package	PG-DSO-14-30			Weight*		143.32 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.599	2.51	2.51	25111	25111
leadframe	inorganic material	phosphorus	7723-14-0	0.015	0.01		105	
	non noble metal	zinc	7440-66-6	0.060	0.04		421	
	non noble metal	iron	7439-89-6	1.207	0.84		8421	
	non noble metal	copper	7440-50-8	49.007	34.19	35.08	341942	350889
wire	noble metal	gold	7440-57-5	0.233	0.16	0.16	1623	1623
encapsulation	organic material	carbon black	1333-86-4	0.171	0.12		1191	
	plastics	epoxy resin	-	7.851	5.48		54780	
	inorganic material	silicondioxide	60676-86-0	77.316	53.95	59.55	539465	595436
leadfinish	non noble metal	tin	7440-31-5	1.226	0.86	0.86	8555	8555
plating	noble metal	silver	7440-22-4	1.030	0.72	0.72	7185	7185
glue	plastics	acrylic resin	-	0.353	0.25		2464	
	noble metal	silver	7440-22-4	1.252	0.87	1.12	8737	11201
*deviation	< 10%	Sum in total:			100,00		1000000	

Important Remarks:

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